



# MJ N-Channel Super Trench Power MOSFET

# Description

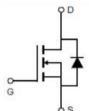
The MJXP4045GU uses Super Trench technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of R<sub>DS(ON)</sub> and Q<sub>g</sub>. This device is ideal for high-frequency switching and synchronous rectification.

#### General Features

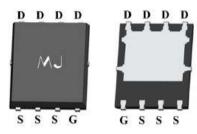
- ♦ V<sub>DS</sub>=40V,I<sub>D</sub>=45A R<sub>DS(ON)</sub>=6.0mΩ (typical) @ V<sub>GS</sub>=10V R<sub>DS(ON)</sub>=8.5mΩ (typical) @ V<sub>GS</sub>=4.5V
- ◆ Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- ◆ Very low on-resistance R<sub>DS(on)</sub>
- ◆ 150°C operating temperature
- ◆ Pb-free lead plating
- ◆ 100% UIS tested

# Application

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification







Top View

**Bottom View** 

## 100% UIS TESTED! 100% ΔVds TESTED!

# Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity	
MJXP4045GU	MJXP4045GU	DFN5X6-8L	4	-	2	

## Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Parameter	Symbol Limit  VDS 40		Unit
Drain-Source Voltage	VDS	40	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	ΙD	45	А
Drain Current-Continuous(Tc =100℃)	ID(100°C)	31.8	А
Pulsed Drain Current	Ідм	125	А
Maximum Power Dissipation	Po	28	W
Derating factor		0.22	W/°C
Single pulse avalanche energy (Note 5)	Eas	115	mJ
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 150	°C

#### Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	Rөjc	4.5	°C/W
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# Electrical Characteristics (Tc=25℃ unless otherwise noted)

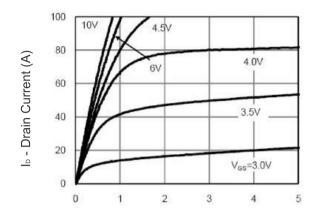
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	'	1				
Drain-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	40	_	-	V
Zero Gate Voltage Drain Current	loss	V <sub>DS</sub> =40V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	lgss	V <sub>DS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	1.0	1.6	2.0	V
Davis Course On Otata Basistan	_	Vgs=10V, ID=20A	-	6	6.6	mΩ
Drain-Source On-State Resistance	RDS(ON)	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	8.5	10	Ω
Forward Transconductance	grs	V <sub>DS</sub> =5V,I <sub>D</sub> =20A	-	30	-	S
Dynamic Characteristics (Note 4)						1
Input Capacitance	Clss	V <sub>DS</sub> =20V,V <sub>GS</sub> =0V F=1.0MHz	-	831	_	PF
Output Capacitance	Coss		-	318	-	PF
Reverse Transfer Capacitance	Crss		-	24	_	PF
Switching Characteristics (Note 4)	'	1				
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =20V,I <sub>D</sub> =20A V <sub>GS</sub> =10V,R <sub>G</sub> =1.6Ω	-	6	-	nS
Turn-on Rise Time	tr		-	2.8	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	23	-	nS
Turn-Off Fall Time	<b>t</b> f		_	3	-	nS
Total Gate Charge	Qg	V <sub>DS</sub> =20V,I <sub>D</sub> =20A V <sub>GS</sub> =10V	-	17.6	-	nC
Gate-Source Charge	Qgs		_	3.5	-	nC
Gate-Drain Charge	Qgd		_	3.1	_	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	Vsp	V <sub>GS</sub> =0V,I <sub>S</sub> =20A	_	_	1.2	V
Diode Forward Current (Note 2)	Is	,	_	_	20	A
Reverse Recovery Time	trr		_	11	_	nS
		TJ=25°C, IF=Is di/dt=100A/µs (Note 3)			_	
Reverse Recovery Charge	Qrr		_	19	_	nC

# Notes:

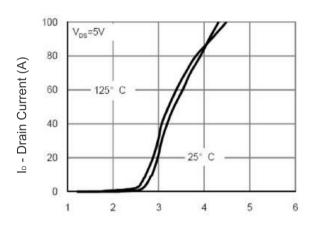
- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300 $\mu$ s, Duty Cycle ≤ 2%.
- 4 Guaranteed by design, not subject to production



# Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)
Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics

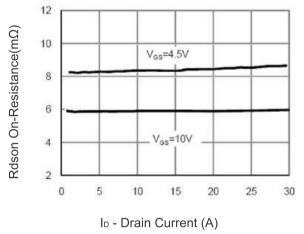
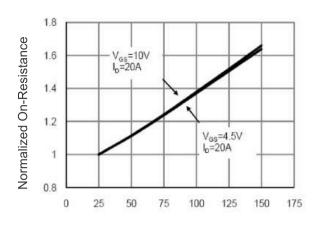
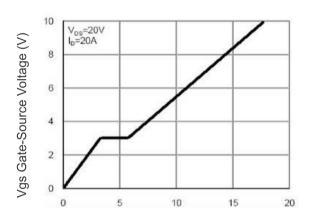


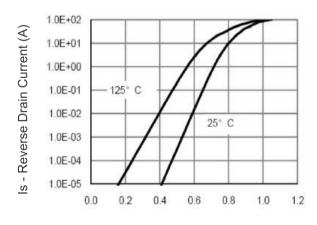
Figure 3 Rdson- Drain Current



TJ -Junction Temperature(°C)
Figure 4 Rdson-Junction Temperature

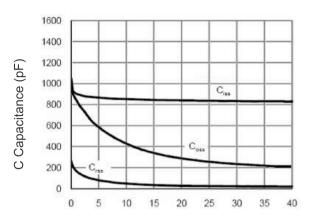


Qg Gate Charge (nC)
Figure 5 Gate Charge

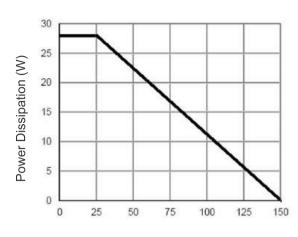


Vsd Source-Drain Voltage (V)
Figure 6 Source- Drain Diode Forward





Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



T<sub>J</sub> -Junction Temperature(°C) Figure 9 Power De-rating

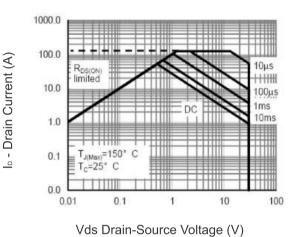
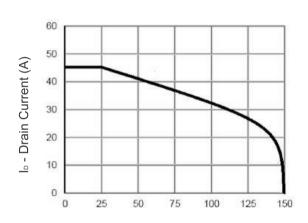
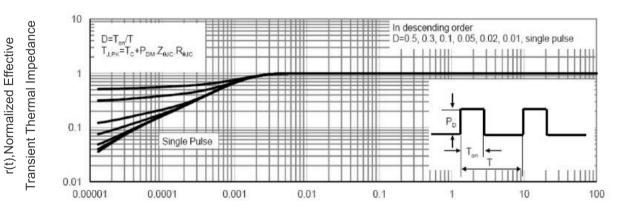


Figure 8 Safe Operation Area



T<sub>J</sub> -Junction Temperature(°C)
Figure 10 Current De-rating



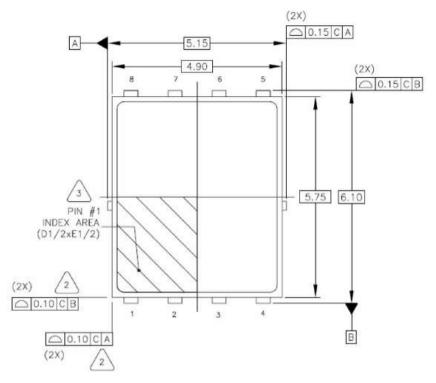
Square Wave Pluse Duration(sec)

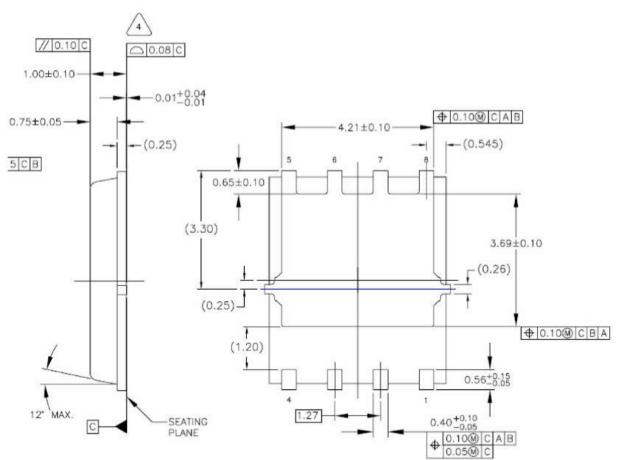
Figure 11 Normalized Maximum Transient Thermal Impedance





# DFN5X6-8L Package Information









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